IN THE CLAIMS

Please amend the claims as follows:

Claim 1-13 (Canceled).

Claim 14 (Currently Amended): A method of eliminating, using a laser beam of laser radiation, pinhole defects lying within a laminate formed from at least a first substrate and from at least a second substrate, the laminate incorporating, between the first and second substrates, at least one ~~smart~~ active system, the method comprising:

locating at least one pinhole defect lying within the active system; and

ablating the pinhole defect through at least one of the first or second substrates, by circumscribing the pinhole defect using the laser beam, the ablating the defect electrically isolating a peripheral region of the pinhole defect relative to the active system including the pinhole defect.

Claim 15 (Currently Amended): The method as claimed in claim 14, wherein the pinhole defect is circumscribed using a continuous laser beam.

Claim 16 (Currently Amended): The method as claimed in claim 14, wherein the pinhole defect is circumscribed using a number of laser pulses.

Claim 17 (Currently Amended): The method as claimed in claim 14, wherein the locating the pinhole defect is carried out by an optical mechanism, either manually by human intervention or automatically using image processing software.

Claim 18 (Currently Amended): The method as claimed in claim 14, further comprising pinpointing the pinhole defect using at least a first laser beam pulse.

Claim 19 (Currently Amended): The method as claimed in claim 18, wherein the pinpointing incorporates resetting the laser beam according to a deviation between the at least first pulse and the pinhole defect.

Claim 20 (Currently Amended): The method as claimed in either of claim 19, wherein the pinpointing is carried out using a [[low]] lower power level of the laser beam than during the ablating.

Claim 21 (Currently Amended): The method as claimed in claim 14, wherein the ablating the pinhole defect moves the laser beam to follow approximately a periphery of the pinhole defect.

Claim 22 (Previously Presented): The method as claimed in claim 14, wherein a wavelength of the laser beam is adapted so that the laser beam is absorbed by layers forming the active system and transmitted through the first and second substrates.

Claim 23 (Currently Amended): The method as claimed in claim 14, wherein the ablating the pinhole defect is carried out through the first substrate.

Claim 24 (Currently Amended): The method as claimed in claim 14, wherein ablating the pinhole defect is carried out through the second substrate.

Claim 25 (Currently Amended): A glazing comprising:

at least one of an electrochemical device or an electrically controllable system of glazing type with variable optical and/or energy properties, of a photovoltaic device or within an electroluminescent device, the electrochemical device being inserted between two electrodes positioned on either side, the electrochemical device including a pinhole defect ablated at its peripheral region ~~having been repaired by the method as claimed in claim 14~~, wherein a value of leakage current is reduced by a factor of 10 at a core of margination of the glazing.